

<b>PCN Number:</b>	20230915002.0		<b>PCN Date:</b>	September 15, 2023
<b>Title:</b>	Wafer Sales Inking Process Removal			
<b>Customer Contact:</b>	Change Management team	<b>Dept:</b>	Quality Services	
<b>Change Type:</b>	Probe wafer setup			
<b>Notification Details</b>				
<b>Description of Change:</b>				
Texas Instruments Incorporated is announcing the removal of the manual bond pad inspection and wafer inking process and will move to an automated visual inspection & electronic map flow as follows:				
	<b>Current</b>	<b>New</b>		
Probe Wafer Setup	Manual Bondpad Inspection & Manual Inking	Inkless with Camtek AVI tools for inspection & electronic maps		
<b>Reason for Change:</b>				
Standardization and manufacturing efficiency.				
<b>Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):</b>				
No anticipated impact.				
<b>Changes to product identification resulting from this PCN:</b>				
Bad die will no longer be visually identifiable as inking is removed, electronic maps need to be used to identify the good vs bad die on each wafer.				
<b>Product Affected:</b>				
ADC081S101 MWC	LM138KG-MD8	LM311-MWC	LM71A1-MWA/S1	
DS26LS31C MWC	LM138KG-MW8	LM317A MWC	LM71A1-MWA/S2	
DS26LS32C MWC	LM1458 MWC	LM319 MWA	LM741C-MWC	
LF347 MWC	LM148 MD8	LM324 MWA	LM747 MWC	
LF356 MWC	LM148 MW8	LM334 MWC	LMH6723 MWC	
LF412 MWC	LM158 MD8	LM335A MWC	LMP7716Q MDA	
LF442-MWA	LM158 MW8	LM336-5 MWC	LMP7716Q MWA	
LM111 MD8	LM2588-5.0-MWC	LM350A MWC	LMP7716Q-MDA/S3	
LM111 MW8	LM2660-MWC	LM385-1.2-MWC	LMP8278MWRB	
LM117HVKG MD8	LM2901 MWA	LM555-MWC	LMP8278MWRB-Q1	
LM117KG MD8	LM2904 MWC	LM5575Q0-MWC	LMT01YS	
LM117KG-MW8	LM2904 MWC/MCD0950A	LM6142 MWC	LMX2430-W	
LM134 MDC	LM2904 MWC/MCD1320A	LM71A-MDA/S5	LP2985I30/DWA	
LM136-5.0-MW8	LM2940-5.0-MW8	LM71A-MDO/S5	PLMT01DS	
LM137KG MD8	LM2991 MWC	LM71A-MDO/S5YS		
LM137KG-MW8	LM301A-MWC	LM71A-MWA		

For questions regarding this notice, e-mails can be sent to the Change Management team or your local Field Sales Representative.

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